## Notice of References Cited Application/Control No. 10/608,502 Examiner John A. McPherson Applicant(s)/Patent Under Reexamination ENGELEN ET AL. Page 1 of 1

## **U.S. PATENT DOCUMENTS**

*	•	Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	В	US-			
	С	US-			
	D	US-	<u> </u>		
	E	US-			
	F	US-			
	G	US-			
	Н	US-			
	I	US-			
	J	US-			
	Κ	US-			
	L	US-			
	М	US-			

## FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
*	N	EP 0 667 608 A	08-1995	EP	Reuhman-Huisken	
*	0	JP 2-173285	07-1990	Japan	Arakawa	
*	Ρ	JP 6-302016	10-1994	Japan	Fujimoto	
	σ					
	R					
	S					
	Т					

## **NON-PATENT DOCUMENTS**

	NON-FATENT DOCUMENTS				
*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)			
*	U	Allen R. et al: "Deep U.V. Hardening or Positive Photoresist Patterns" Journal of the Electrochemical Society, vol. 29, no. 6, June 1982, pp. 1379-1381, XP002047660 see pages 1379-1380.			
*	٧	Hiraoka & Pacansky: "UV-hardening of Resist Patterns" IBM Technical Disclosure Bulletin, vol. 24, no. 3, August 1981, page 1468 XP002067935 see page 1468.			
*	w	"Photoresist Stabilization System" Solid State Technology, vol. 27, no. 7, June 1984, pages 45-45, XP002067936 Washington, New York, USA see pages 45-46.			
	x				

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)

Dates in MM-YYYYY format are publication dates. Classifications may be US or foreign.